CLAIMS

1. A heat dissipating device adapted to be mounted on a heat generating object, comprising:

a heat conductive base including a plurality of insertion holes, with at least one heat generating region formed in a contact area between the heat conductive base and a heat source of the heat generating object, with each of the plurality of insertion holes including an engagement portion, with at least one of two ends of each of the plurality of heat dissipating columns having an assembling portion, with the assembling portion of each of the plurality of heat dissipating columns inserted into one of the plurality of insertion holes and engaged with the engagement portion of the one of the plurality of insertion holes; and

a plurality of heat dissipating columns disposed in the at least one heat generating region and respectively inserted into and positioned in the plurality of insertion holes, with each of the plurality of heat dissipating columns including a heat conductive silicone layer disposed on an outer periphery thereof,

with the heat dissipating device characterized in that:

the engagement portion of each of the plurality of insertion holes is one

of a magnetic element and a magnetically attracted structure, and each assembling portion is disposed on an end face of one of the plurality of heat dissipating columns and is another of the magnetic element and the magnetically attracted structure.

2. The heat dissipating device as claimed in claim 1, characterized in that the engagement portion of each of the plurality of insertion holes is an inner thread, and each assembling portion is an outer thread formed on the outer periphery of one of the plurality of heat dissipating columns.

3. The heat dissipating device as claimed in claim 1, characterized in that an entire area of the outer periphery of each of the plurality of heat dissipating columns is enveloped by the heat conductive silicone layer except the assembling portion.

4. The heat dissipating device as claimed in claim 1, characterized in that each of the two ends of each of the plurality of heat dissipating columns has the assembling portion.

5. The heat dissipating device as claimed in claim 4, characterized in that each of the plurality of insertion holes has a depth smaller than a half of a length of each of the plurality of heat dissipating columns.

6. The heat dissipating device as claimed in claim 4, characterized in that the heat conductive base including a first face, a second face opposite to

the first face, and a peripheral face connected between the first and second faces, with a portion of the plurality of insertion holes disposed in the first face, and a remaining portion of the plurality of insertion holes disposed in the peripheral face.

7. The heat dissipating device as claimed in claim 6, characterized in that each of the remaining portion of the plurality of insertion holes disposed in the peripheral face has a depth larger than or equal to a half of a length of each of the plurality of heat dissipating columns.

8. The heat dissipating device as claimed in claim 1, characterized in that the heat conductive silicone layer of each of the plurality of heat dissipating columns has a micro structure.

9. The heat dissipating device as claimed in claim 1, characterized in that the heat conductive silicone layer of each of the plurality of heat dissipating columns further has a graphene layer.

10. The heat dissipating device as claimed in claim 9, characterized in that the graphene layer of each of the plurality of heat dissipating columns has a micro structure.